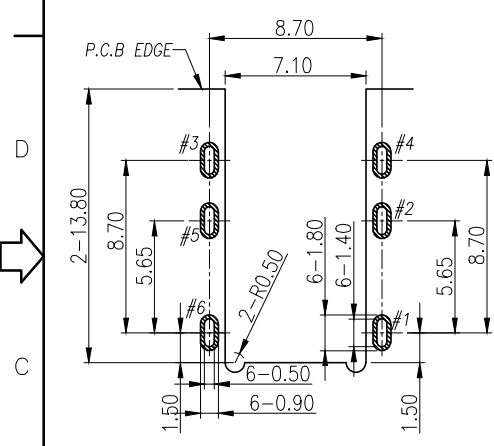
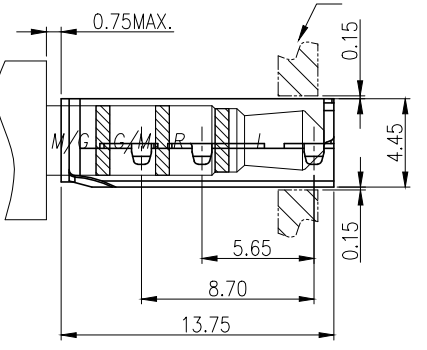
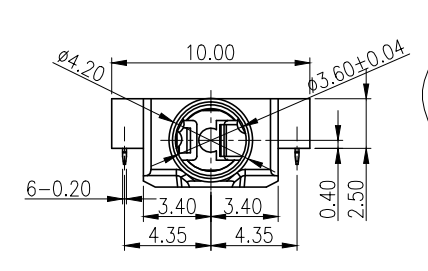
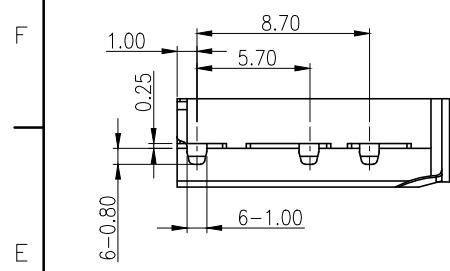
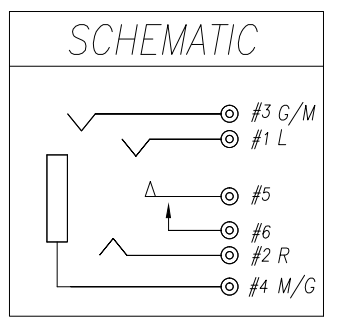
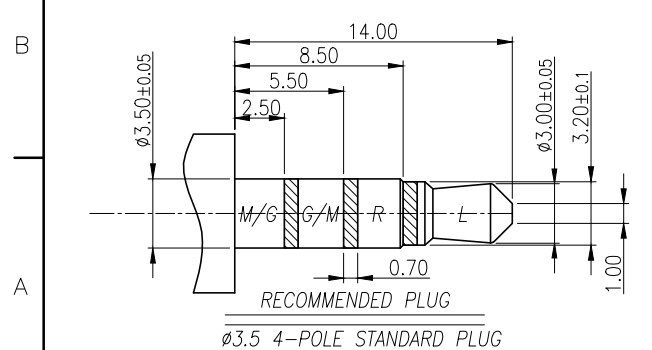
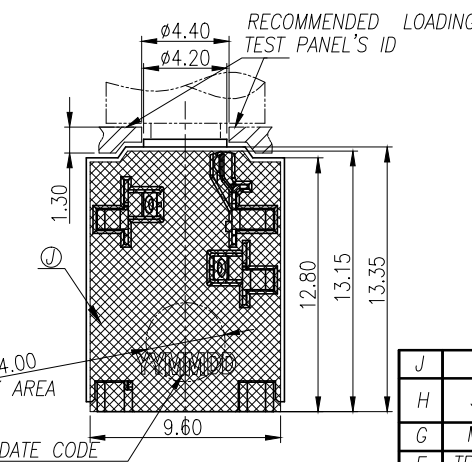
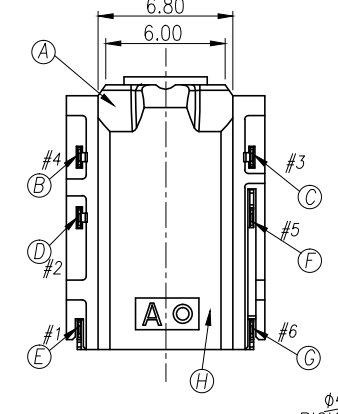


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO:T160616-2A	ROBIN	2016.11.17



RECOMMENDED PCB LAYOUT
TOP VIEW ; TOL.±0.05



- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC .
 - CONTACT RESISTANCE: 50mΩ MAX.
 - INSULATION VOLTAGE WITHSTAND:500V AC FOR ONE MINUTE.
 - UNLESS OTHERWISE SPECIFIED. TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT,IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
 - LIFE TEST: 5,000 CYCLES.
 - INSERTION FORCE: 0.3 - 3.0Kg.
 - WITHDRAWAL FORCE: 0.3 - 3.0Kg.
 - AFTER TEST, CONTACT RESISTANCE: 120mΩ MAX.
 - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
 - MARKING: MARK "S" ON TOP OF CONNECTOR.
 - PACKING : TAPE & REEL.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK:
 - HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:

J	MYLAR	1	KAPTON 0.06t	YELLOW
H	SEPARATOR	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
G	MAKE TERMINAL	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA; GOLD FLASH ON SOLDER AREA; ALL OVER 50u" Ni.
F	TRANSFER TERMINAL	1	COPPER ALLOY, 0.2t	
E	TIP SPRING	1	COPPER ALLOY, 0.2t	
D	RING A	1	COPPER ALLOY, 0.2t	
C	RING B	1	COPPER ALLOY, 0.2t	
B	EARTH	1	COPPER ALLOY, 0.2t	
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES		Singatron Enterprise Co., Ltd. 信音企業股份有限公司	
DECIMALS:	ANGLES:	TITLE	
X :±0.5	X :±2°	3.5Ø PHONE JACK	
X.X :±0.3	X.X :±1°	DWN	ROBIN PART NO. 2SJ3175-000111F
X.XX :±0.2		CHKD	BRUCE SCALE 4:1 UNIT: mm
		APVD	LUSSEN SIZE: A3 SHEET:1 OF 1 REV: A
CUSTOMER COPY			